

PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

A processing apparatus includes a wafer unloading unit, a wafer table, a frame unloading unit, a frame table, a tape affixing unit, a tape-affixed frame transporting unit, a tape compression-bonding unit, a frame unit unloading unit that unloads a frame unit in which a tape of a tape-affixed frame and the undersurface of a wafer are compression-bonded to each other from the wafer table, a reinforcing portion removing unit, a no-ring unit unloading unit, and a frame cassette table.

Figure 1